Dual Up Counters

The MC14518B dual BCD counter and the MC14520B dual binary counter are constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each consists of two identical, independent, internally synchronous 4-stage counters. The counter stages are type D flip-flops, with interchangeable Clock and Enable lines for incrementing on either the positive-going or negative-going transition as required when cascading multiple stages. Each counter can be cleared by applying a high level on the Reset line. In addition, the MC14518B will count out of all undefined states within two clock periods. These complementary MOS up counters find primary use in multi-stage synchronous or ripple counting applications requiring low power dissipation and/or high noise immunity.

Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Internal and External Speeds
- Logic Edge-Clocked Design Incremented on Positive Transition of Clock or Negative Transition on Enable
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 1.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 2.)	500	mW
T _A	Operating Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Maximum Ratings are those values beyond which damage to the device may occur.
- 2. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.



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MARKING DIAGRAMS

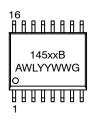


PDIP-16 P SUFFIX CASE 648





SO-16 WB DW SUFFIX CASE 751G





SOEIAJ-16 F SUFFIX CASE 966



xx = 18 or 20

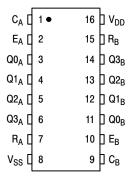
A = Assembly Location

 $\begin{array}{lll} WL, L &= Wafer \, Lot \\ YY, Y &= Year \\ WW, W &= Work \, Week \\ G &= Pb-Free \, Indicator \end{array}$

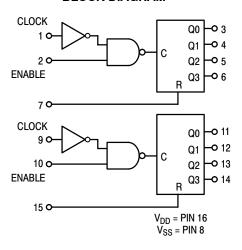
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

PIN ASSIGNMENT



BLOCK DIAGRAM



TRUTH TABLE

Clock	Enable	Reset	Action	
	1	0	Increment Counter	
0	~	0	Increment Counter	
~	Х	0	No Change	
Х		0	No Change	
	0	0	No Change	
1	~	0	No Change	
Х	Х	1	Q0 thru Q3 = 0	

X = Don't Care

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ ^(3.)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	"0" Level	V _{IL}	5.0 10 15	_ _ _	1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
(V _O = 0.5 or 4.5 Vdc) (V _O = 1.0 or 9.0 Vdc) (V _O = 1.5 or 13.5 Vdc)	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15		5.0 10 20		0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current (4.) (5 (Dynamic plus Quiesco Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	I _T	5.0 10 15			$I_T = (1$	J.6 μΑ/kHz) f I.2 μΑ/kHz) f I.7 μΑ/kHz) f	+ I _{DD}	,		μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.002.

SWITCHING CHARACTERISTICS (6.) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

				All Types		
Characteristic	Symbol	V_{DD}	Min	Typ ^(7.)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_L + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_L + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_L + 9.5 \text{ ns} \\ \end{cases}$	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q/Enable to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 215 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_{L} + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	280 115 80	560 230 160	ns
Reset to Q $t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 265 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 117 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 95 \text{ ns}$	t _{PHL}	5.0 10 15	_ _ _	330 130 90	650 230 170	ns
Clock Pulse Width	t _{w(H)} t _{w(L)}	5.0 10 15	200 100 70	100 50 35	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	2.5 6.0 8.0	1.5 3.0 4.0	MHz
Clock or Enable Rise and Fall Time	t _{THL} , t _{TLH}	5.0 10 15	_ _ _	_ _ _	15 5 4	μs
Enable Pulse Width	t _{WH(E)}	5.0 10 15	440 200 140	220 100 70	_ _ _	ns
Reset Pulse Width	t _{WH(R)}	5.0 10 15	280 120 90	125 55 40	_ _ _	ns
Reset Removal Time	t _{rem}	5.0 10 15	- 5 15 20	- 45 - 15 - 5	_ _ _	ns

^{6.} The formulas given are for the typical characteristics only at 25°C.7. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

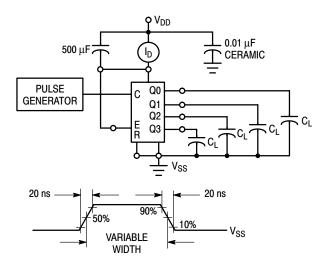


Figure 1. Power Dissipation Test Circuit and Waveform

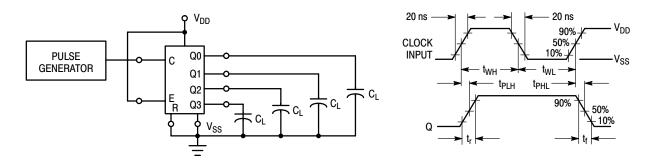


Figure 2. Switching Time Test Circuit and Waveforms

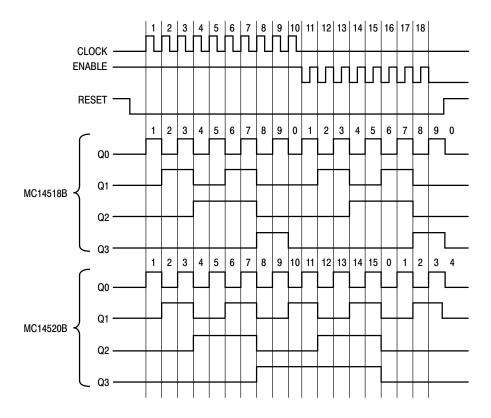


Figure 3. Timing Diagram

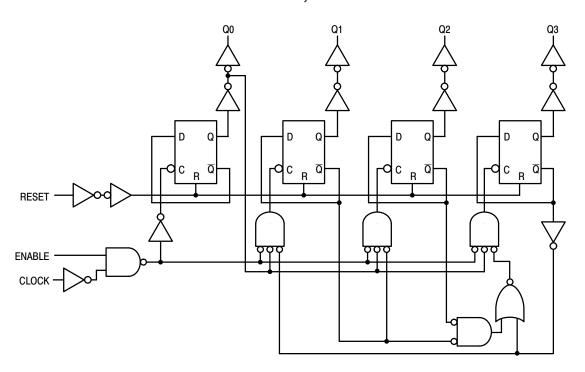


Figure 4. Decade Counter (MC14518B) Logic Diagram (1/2 of Device Shown)

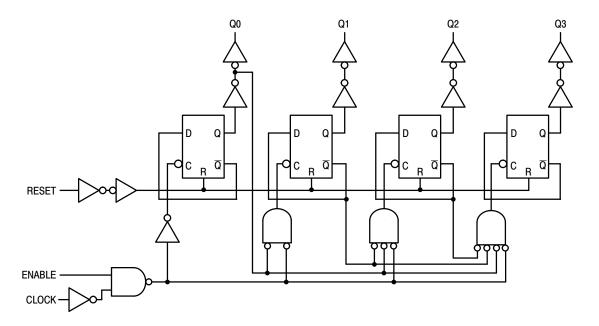


Figure 5. Binary Counter (MC14520B) Logic Diagram (1/2 of Device Shown)

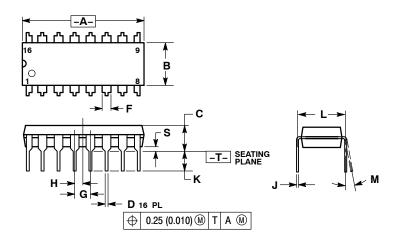
ORDERING INFORMATION

Device	Package	Shipping [†]	
MC14518BCPG	PDIP-16 (Pb-Free)	500 Units / Rail	
MC14518BDWG	SO-16 WB (Pb-Free)	47 Units / Rail	
MC14518BDWR2G	SO-16 WB	1000 Units / Tape & Reel	
NLV14518BDWR2G*	(Pb-Free)		
MC14518BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel	
MC14520BCPG	PDIP-16 (Pb-Free)	500 Units / Rail	
MC14520BDWG	SO-16 WB (Pb-Free)	47 Units / Rail	
MC14520BDWR2G	SO-16 WB (Pb-Free)	1000 Units / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP

PACKAGE DIMENSIONS

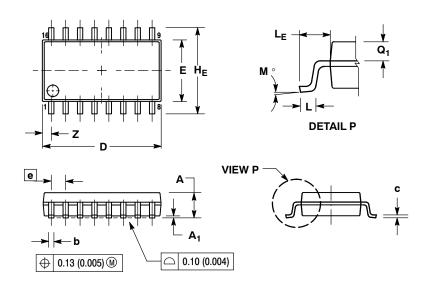
PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING F ANSI Y14-5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE
- MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE A**



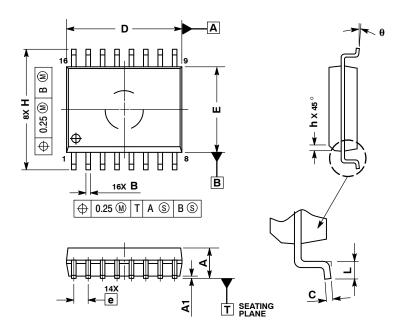
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- OR PROTRUSIONS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION IOIAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	BSC 0.050 BSC	
ΗE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q_	0.70	0.90	0.028	0.035
Z		0.78		0.031

PACKAGE DIMENSIONS

SOIC-16 WB CASE 751G-03 ISSUE D



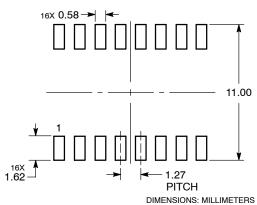
NOTES:

- DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES
- PER ASME Y14.5M, 1994.

 3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS				
DIM	MIN	MAX			
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
С	0.23	0.32			
D	10.15	10.45			
E	7.40	7.60			
е	1.27 BSC				
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
а	0 °	7 °			

SOLDERING FOOTPRINT



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